

Title (en)
COMPOSITIONS FOR BIPOLAR PLATES AND METHODS FOR MANUFACTURING SAID COMPOSITIONS

Title (de)
ZUSAMMENSETZUNGEN FÜR BIPOLARE PLATTEN UND VERFAHREN ZUR HERSTELLUNG DER BESAGTEN ZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS POUR PLAQUES BIPOLAIRES ET METHODES DE FABRICATION DE CES COMPOSITIONS

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Abstract (en)
[origin: WO2020058627A1] The present invention relates to new compositions for bipolar plates and to methods for manufacturing said compositions. More specifically, the invention relates to a method for manufacturing a composition, comprising the following steps: mixing a thermoplastic polymer in the molten state with a first conductive charge in order to obtain a conductive thermoplastic polymer; grinding said conductive thermoplastic polymer in order to reduce it to a powder; mixing the conductive thermoplastic polymer powder with a second conductive charge.

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